holding portion being wider than the wiring path;

laying a wire in the wiring path of the wiring board such that a leader of the wire, including any bent portion thereof, is held in the holding portion of the wiring board as the wire is laid; and

combining the first and second casings with the wiring board located therebetween.

- 10. (New) The method according to claim 9, wherein said wiring path comprises a laying groove, and said holding portion comprises a holding recess that is wider than the laying groove.
- 11. (New) The method according to claim 9, wherein said holding recess is extended on both sides of the laying groove in a width direction of the laying groove.--